

CH55x Reset Controller

2023-10 RevB1

BLIN
KIN
LABS

PC

U1

D1 R15

C5

R2

Q2

D2 R16

R5

R6

R3

R8

R9

Q3

Q1

C3

U3

C4

R7

C2

C1

U2

R4

R1

R14

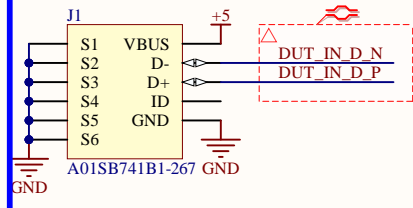
DUT

Bootloader

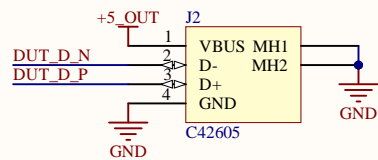
Remote

CH55x Reset Controller

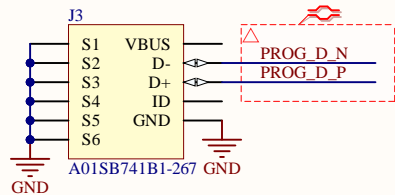
DUT micro USB input



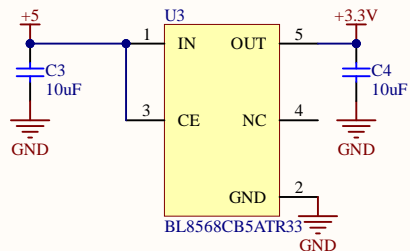
DUT USB A output



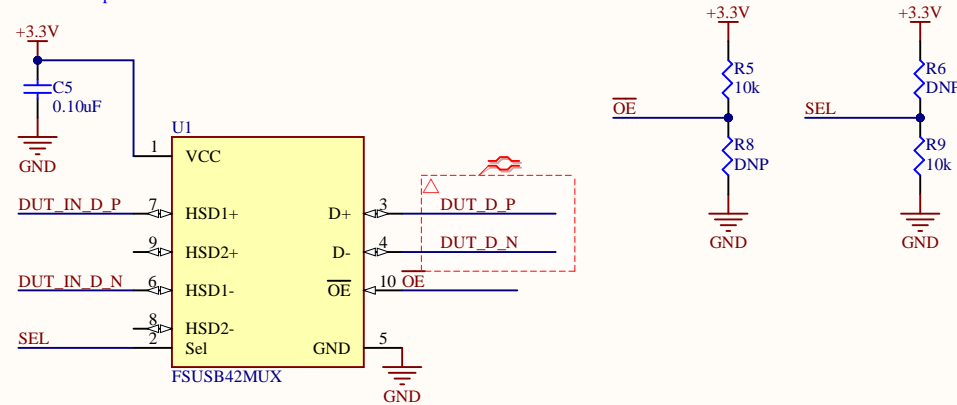
Switch control Micro USB input



3.3V regulator

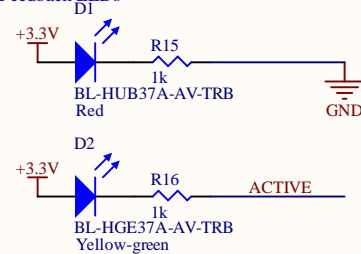


USB mux chip

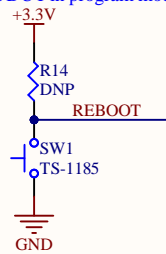


Need to test if SEL or OE works best

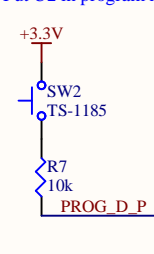
Feedback LEDs



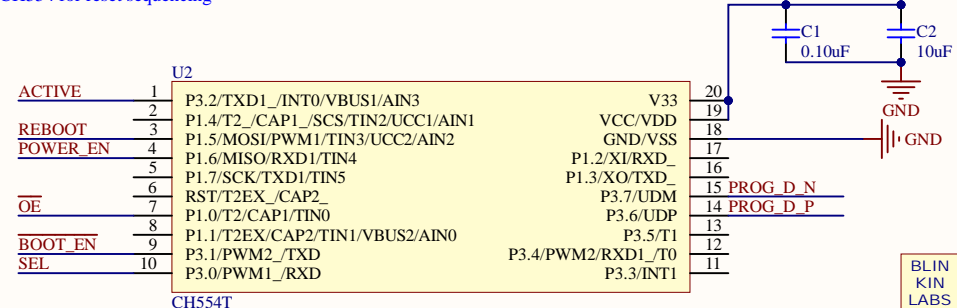
Put DUT in program mode



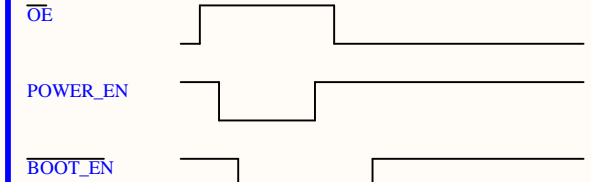
Put U2 in program mode



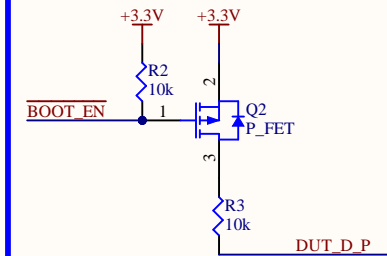
CH554 for reset sequencing



Reboot sequence

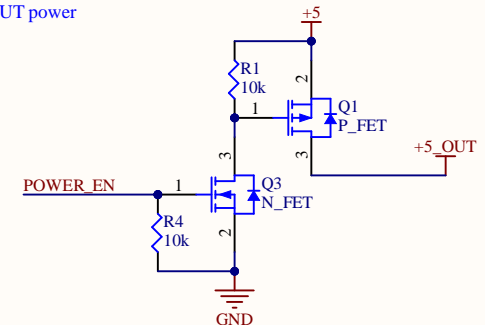


D+ pullup



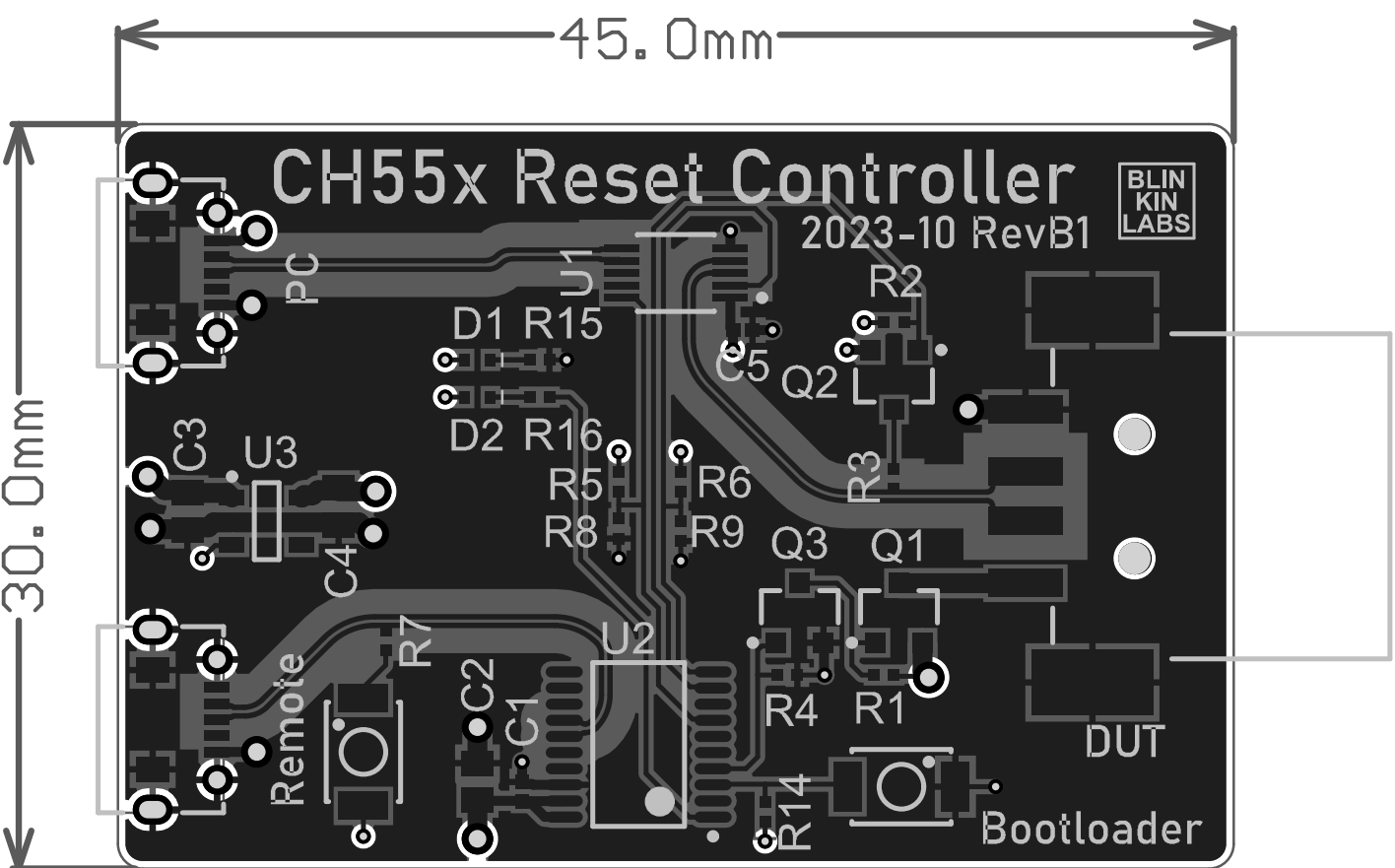
When BOOT_EN is high, Q2 is off and R3 is left floating
When BOOT_EN is low, Q2 is on and R3 is connected to 3.3V

DUT power



When POWER_EN is high, Q3 is on, Q1 is on, so +5V out is +5V
When POWER_EN is low, Q3 is off, Q1 is off, so +5V_OUT is floating

CH55x Reset Controller



Silkscreen: white / don't care
Soldermask: green / don't care
Surface finish: ENIG
Copper weight: 1oz outer, 0.5oz inner

Layer	Name	Material	Thickness	Constant
	Top Overlay			
	Top Solder	SM-001	0.013mm	4
1	Top Layer	CF-004	0.035mm	
	Dielectric 2	PP-022	0.200mm	4.6
2	Layer 1	CF-004	0.015mm	
	Dielectric 3	Core-039	0.700mm	4.8
3	Layer 2	CF-004	0.015mm	
	Dielectric 4	PP-022	0.200mm	4.6
4	Bottom Layer	CF-004	0.035mm	
	Bottom Solder	SM-001	0.013mm	4
	Bottom Overlay			

Total board thickness: 1.226mm

Design Rules Verification Report

Filename : C:\Users\matt\repos\ch55x_programmer\pcb\PCB1.PcbDoc

Warnings 0
Rule Violations 62

Warnings	
Total	0

Rule Violations	
Clearance Constraint (Gap=0.2mm) (All),(All)	0
Clearance Constraint (Gap=0.127mm)	0
Clearance Constraint (Gap=1mm) (InDifferentialPairClass('D90')),(InPolygon)	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint ((All))	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.2mm) (Max=0.8mm) (Preferred=0.4mm) (All)	0
Power Plane Connect Rule(Relief Connect)(Expansion=0.508mm) (Conductor Width=0.254mm)	0
Hole Size Constraint (Min=0.025mm) (Max=2.54mm) (All)	0
Hole To Hole Clearance (Gap=0.254mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)	39
Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)	9
Silk to Silk (Clearance=0.254mm) (All),(All)	5
Net Antennae (Tolerance=0mm) (All)	0
Board Clearance Constraint (Gap=0mm) (All)	9
Room Sheet1 (Bounding Region = (120.775mm, 77.5mm, 184mm, 122.5mm)	0
Height Constraint (Min=0mm) (Max=25.4mm) (Preferred=12.7mm) (All)	0
Total	62

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.254mm) Between Pad C1-1(16.3mm,2.71mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad C4-1(8.9mm,15.35mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad C4-2(8.9mm,13.85mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.176mm < 0.254mm) Between Pad C4-2(8.9mm,13.85mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.254mm) Between Pad C5-1(24.81mm,21.7mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad J1-D-(4mm,24.65mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad J1-D-(4mm,24.65mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad J1-D+(4mm,24mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad J1-GND(4mm,22.7mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.122mm < 0.254mm) Between Pad J1-GND(4mm,22.7mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.122mm < 0.254mm) Between Pad J1-S4(4mm,26.425mm) on Multi-Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad J3-D-(4mm,6.65mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad J3-D-(4mm,6.65mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad J3-D+(4mm,6mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad J3-GND(4mm,4.7mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.122mm < 0.254mm) Between Pad J3-GND(4mm,4.7mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.122mm < 0.254mm) Between Pad J3-S4(4mm,8.425mm) on Multi-Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R1-1(30.5mm,7.8mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R14-1(26.1mm,2.7mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R15-1(16.6mm,20.5mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R16-1(16.6mm,19mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R2-1(31.7mm,22mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R3-1(31.3mm,15.3mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R4-1(27.4mm,7.8mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R5-1(20.2mm,15.2mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R6-1(22.7mm,15.2mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R7-1(10.8mm,9.6mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R8-1(20.2mm,13.3mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R9-1(22.7mm,13.2mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-1(24.7mm,23mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-10(20.3mm,23mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-2(24.7mm,23.5mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-3(24.7mm,24mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-4(24.7mm,24.5mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-6(20.3mm,25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-7(20.3mm,24.5mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.2mm < 0.254mm) Between Pad U1-8(20.3mm,24mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad U3-1(4.6mm,14.95mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad U3-2(4.6mm,14mm) on Top Layer And Pac

Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Arc (32.7mm,4.3mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Arc (8.9mm,5.8mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.225mm < 0.254mm) Between Pad D1-2(15.025mm,20.5mm) on Top Layer Anc
Silk To Solder Mask Clearance Constraint: (0.225mm < 0.254mm) Between Pad D2-2(15.025mm,19mm) on Top Layer Anc
Silk To Solder Mask Clearance Constraint: (0.175mm < 0.254mm) Between Pad J2-5(39.3mm,22.5mm) on Top Layer Anc
Silk To Solder Mask Clearance Constraint: (0.175mm < 0.254mm) Between Pad J2-6(39.3mm,7.5mm) on Top Layer Anc
Silk To Solder Mask Clearance Constraint: (0.242mm < 0.254mm) Between Pad R9-1(22.7mm,13.2mm) on Top Layer Anc
Silk To Solder Mask Clearance Constraint: (0.242mm < 0.254mm) Between Pad R9-2(22.7mm,14mm) on Top Layer And Tex
Silk To Solder Mask Clearance Constraint: (0.253mm < 0.254mm) Between Pad U1-10(20.3mm,23mm) on Top Layer Anc

Silk to Silk (Clearance=0.254mm) (All),(All)

Silk To Silk Clearance Constraint: (0.106mm < 0.254mm) Between Text "BLIN

KIN**LABS" (40.4mm,25.4mm) on Top Overlay And Track (40.4mm,25.4mm)(40.4mm,28.4mm) on Top Overl****Silk to Silk (Clearance=0.254mm) (All),(All)**

Silk To Silk Clearance Constraint: (0.176mm < 0.254mm) Between Text "BLIN

KIN**LABS" (40.4mm,25.4mm) on Top Overlay And Track (40.4mm,25.4mm)(43.4mm,25.4mm) on Top Overl****Silk to Silk (Clearance=0.254mm) (All),(All)**

Silk To Silk Clearance Constraint: (0.176mm < 0.254mm) Between Text "BLIN

KIN**LABS" (40.4mm,25.4mm) on Top Overlay And Track (40.4mm,28.4mm)(43.4mm,28.4mm) on Top Overl****Silk to Silk (Clearance=0.254mm) (All),(All)**

Silk To Silk Clearance Constraint: (0.106mm < 0.254mm) Between Text "BLIN

KIN**LABS" (40.4mm,25.4mm) on Top Overlay And Track (43.4mm,25.4mm)(43.4mm,28.4mm) on Top Overl****Silk to Silk (Clearance=0.254mm) (All),(All)**

Silk To Silk Clearance Constraint: (0.247mm < 0.254mm) Between Text "U2" (19.575mm,8.669mm) on Top Overlay And Trac

Board Clearance Constraint (Gap=0mm) (All)

Board Outline Clearance(Outline Edge): (Collision < 0.1mm) Between Board Edge And Track

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Board Outline Clearance(Outline Edge): (Collision < 0.1mm) Between Board Edge And Track

Electrical Rules Check Report

Class	Document	Message
Warning	Sheet1.SchDoc	Net O\E\ has no driving source (Pin R5-1, Pin R8-2, Pin U1-10, Pin U2-7)
Warning	Sheet1.SchDoc	Un-Designated Part L?

